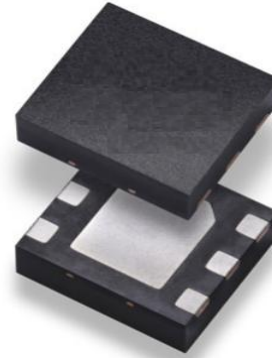


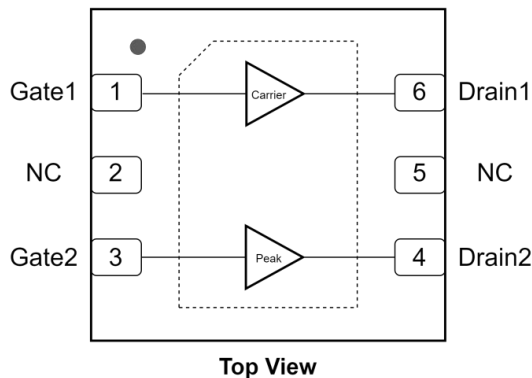
Description

The HTH2D49P060P is a GaN Asymmetrical Doherty Power Amplifier designed for cellular base station applications with 60W saturation output power covering frequency range from 4.5 to 5.0 GHz.



DFN 7*6.5 Package

Block Diagram



Features

- Operating Frequency Range: 4.5 to 5.0 GHz
- Operating Drain Voltage: +48 V
- Saturation Output Power: 60 W
- Advanced Linearity Performance
- High Efficiency
- High terminal impedance for optimal broadband performance
- High reliability
- Small footprint package, DFN 7 x 6.5mm

Applications

- 3GPP 5G NR FR1 N79 and 4G/LTE band B79.
- Power Amplifier for Small cells.
- Driver Amplifier for macro base stations.
- Active antenna array for 5G mMIMO.
- Repeaters/DAS.

Order Information

Part Number	Description
HTH2D49P060P	Reel Package

Typical Performances

Freq (MHz)	P5dB (dBm)	Gain (dB)	Eff (%)	IRL (dB)
4500	48.7	15.0	43.2	15
4600	48.7	15.5	45.4	13
4700	48.7	15.3	46.4	13
4800	48.7	14.8	46.4	13
4900	48.5	14.1	45.6	12
5000	48.1	13.8	46.6	12

Test conditions unless otherwise noted: 25 °C, VDD = 48V, IDQ = 35mA, Vgsp = Vgsp[1] - 1.8V, Pout = 39.4dBm, Pulse Width = 100 us, Duty Cycle = 10% test on WATECH EVB.

[1] IDQ_Peak=40mA

Freq(MHz)	Gain(dB)	Eff(%)	ACPR 5MHz(dBc)	ACPR 10MHz(dBc)
4500	13.5	44.9	-26.8	-44.2
4600	14.2	46.5	-29.6	-46.4
4700	14.1	45.8	-33.9	-48.8
4800	13.9	44.8	-37.9	-49.2
4900	13.2	44.2	-38.1	-49.2
5000	12.9	45.0	-37.9	-49.3

Test conditions unless otherwise noted: 25 °C, VDD = 48V, IDQ = 35mA, Vgsp=Vgsp[1] - 1.8V, PAVG = 39.4 dBm 1C-WCDMA 5MHz Signal, 9.9 dB PAR @ 0.01% CCDF test on WATECH EVB.

Carrier LoadPull Performance

Max Output Power						
Freq (MHz)	Z_source (Ω)	Z_load [1] (Ω)	Gain (dB)	P5dB (dBm)	P5dB (W)	Eff (%)
4500	23.5 + j*59.7	9.4 - j*10.8	18.0	46.21	41.8	63.8
4700	29.1 + j*30.1	8.8 - j*11.2	17.8	46.24	42.1	65.2
5000	76.6 - j*10.9	9.1 - j*11.0	17.8	46.26	42.3	68.4
Max Drain Efficiency						
Freq (MHz)	Z_source (Ω)	Z_load [2] (Ω)	Gain (dB)	P5dB (dBm)	P5dB (W)	Eff (%)
4500	20.4 + j*58.6	5.8 - j*8.2	19.7	45.22	33.3	72.4
4700	28.7 + j*27.6	6.5 - j*7.9	19.3	45.30	33.9	72.7
5000	83.0 - j*15.6	6.4 - j*8.0	19.0	45.15	32.7	74.4

Test conditions unless otherwise noted: 25 °C, VDD = 48V, Idq = 35mA, Pulsed CW, 1000 us, Duty Cycle = 4%, Test on Watech Loadpull fixture.

Peak LoadPull Performance

Max Output Power						
Freq (MHz)	Z_source (Ω)	Z_load [1] (Ω)	Gain (dB)	P5dB (dBm)	P5dB (W)	Eff (%)
4500	18.0 + j*84.2	7.0 - j*15.8	16.7	47.69	58.7	63.5
4700	19.3 + j*55.2	5.7 - j*16.2	17.1	47.81	60.4	68.4
5000	26.9 + j*21.7	6.5 - j*16.8	16.5	47.77	59.8	66.5
Max Drain Efficiency						
Freq (MHz)	Z_source (Ω)	Z_load [2] (Ω)	Gain (dB)	P5dB (dBm)	P5dB (W)	Eff (%)
4500	17.6 + j*83.0	6.0 - j*12.7	17.5	46.91	49.1	68.3
4700	19.4 + j*53.2	5.5 - j*13.9	17.7	47.17	52.1	72.3
5000	27.9 + j*20.2	6.3 - j*14.4	16.7	47.15	51.9	67.5

Test conditions unless otherwise noted: 25 °C, VDD = 48V, Idq = 50mA, Pulsed CW, 1000 us, Duty Cycle = 4%, Test on Watech Loadpull fixture.

[1] Load impedance for optimum P5dB Pout

[2] Load impedance for optimum P5dB efficiency

Absolute Maximum Ratings

Parameter	Range/Value	Units
Drain voltage (VDSS)	0 to +150	V
Gate voltage (VGS)	-15 to =2	V
Storage Temperature (TSTG)	-55 to 150	°C
Case Temperature (TC)	-40 to 150	°C
Junction Temperature (TJ)	+275	°C

Electrical Specification

DC Characteristics Carrier

Parameter	Conditions	Min	Typ	Max	Units
Breakdown Voltage V(BR)DSS	VGS=-8V; IDS=3.5mA	150	-	-	V
Gate-Source threshold Voltage VGS(th)	VDS=6V; IDS=3.5mA	-3.8	-2.8	-2.2	V
Drain leakage Current IDSS	VDS=50V; VGS=-10V	-	-	0.7	mA
Gate leakage Current IGSS	VDS=0V; VGS=-8V	-	-	0.35	mA

DC Characteristics Peak

Parameter	Conditions	Min	Typ	Max	Units
Breakdown Voltage V(BR)DSS	VGS=-8V; IDS=5.0mA	150	-	-	V
Gate-Source threshold Voltage VGS(th)	VDS=6V; IDS=5.0mA	-3.8	-2.8	-2.2	V
Drain leakage Current IDSS	VDS=50V; VGS=-10V	-	-	1.0	mA
Gate leakage Current IGSS	VDS=0V; VGS=-8V	-	-	0.5	mA

RF Characteristics (Pulsed CW)

Parameter	Conditions	Min	Typ	Max	Units
P5dB	Freq=4.9GHz	47.5	48.5	-	dBm
Gain@39.4dBm	Freq=4.9GHz	11	13.5	-	dB
Eff@39.4dBm	Freq=4.9GHz	42	46	-	%
IRL	Freq=4.9GHz	10	12	-	dB
Parameter	Conditions	Min	Typ	Max	Units
P5dB	Freq=5.0GHz	47.5	48.3	-	dBm
Gain@39.4dBm	Freq=5.0GHz	11	13.5	-	dB
Eff@39.4dBm	Freq=5.0GHz	40	44	-	%
IRL	Freq=5.0GHz	10	12	-	dB

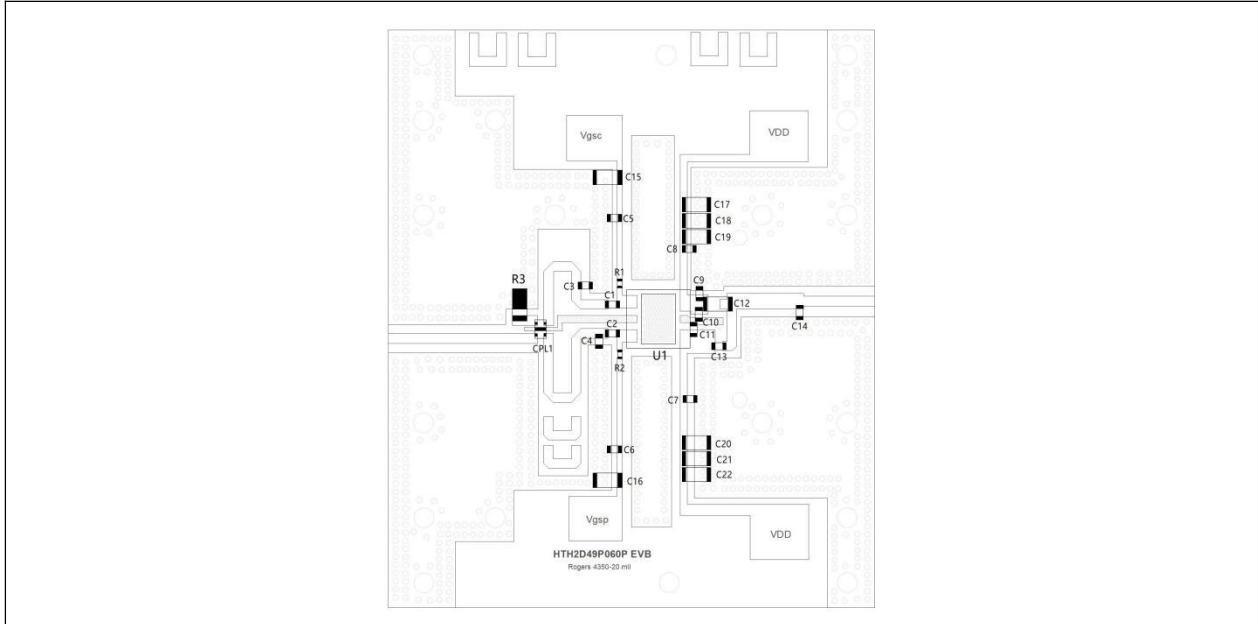
Test conditions, unless otherwise noted: 25 °C, VDD = 48V, IDQ = 35 mA, Vgsp = Vgsp[1]-2.2V, Pulse Width = 1000 us, Duty Cycle = 5%, test on FT board with compensation.

[1] IDQ_Peak=40mA

Thermal Information

Symbol	Parameter	Conditions	Value (Typ)	Units
Rth(s-c)(IR)	Thermal resistance from active Die Surface to Case by Infrared measurement	T-Case = 125°C, Pdiss = 14W	4.0	K/W
Rth(ch-c)(FEA)	Thermal resistance from active Die Channel to Case by Finite Element Analysis	T-Case = 125°C, Pdiss = 14W	6.1	K/W

HTH2D49P060P 4.5-5.0 GHz Reference Design



EVB Layout

Rogers 4350B, thickness=20mil

PCB is soldered on a 54 mm by 64 mm copper base plate with 10 mm thickness

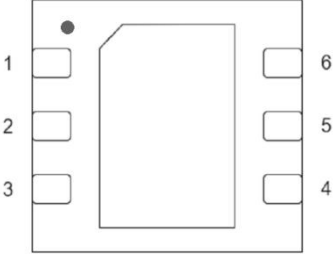
BOM-HTH2D49P060P 4.5 – 5.0 GHz Reference Design

Component	Type	Value	Description	Manufacturer	P/N
U1	Transistor	/	GaN transistor	WATECH	HTH2D49P060P
C1,C2	Capacitor	1.0pF	0603 MLCC	Murata	GQM1875G2E1R0BB12
C3,C4	Capacitor	0.4pF	0603 MLCC	Murata	GQM1875G2ER40BB12
C5,C6,C7	Capacitor	1.8pF	0603 MLCC	Murata	GQM1875G2E1R8BB12
C8	Capacitor	1.2pF	0603 MLCC	Murata	GQM1875G2E1R2BB12
C9,C10,C11	Capacitor	0.5pF	0603 MLCC	Murata	GQM1875G2ER50BB12
C12	Capacitor	0.8pF	0805 MLCC	Murata	GQM2195G2ER80BB12
C13	Capacitor	1.0pF	0603 MLCC	Murata	GQM1875G2E1R0BB12
C14	Capacitor	0.1pF	0603 MLCC	Murata	GQM1875G2ER10BB12
C15-C22	Capacitor	1uF	0805 MLCC	Murata	GRM21BC72A105KE01L
R1,R2	Resistor	10 Ω	0402 Resistor	YAGEO	RC0402JR-100RL
R3	Resistor	50 Ω	16 Watts, 50Ω	Anaren	C16A50Z4
CPL1	Coupler	3dB	Hybrid Coupler	Anaren	X4C45J1-03S

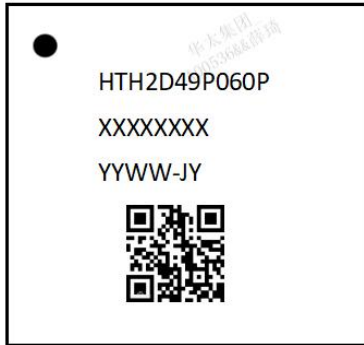
Performance Plots

<p style="text-align: center;">Gain&Eff vs Pout</p>	<p style="text-align: center;">S Parameters</p>
<p>Pulsed-CW performance(Gain+Eff)</p> <p><i>Test conditions, unless otherwise noted: 25 °C, VDD = 48 V, IDQ = 35 mA, Vgsp = Vgsp[1] - 1.8V, Pulse Width = 100 us, Duty Cycle = 10%, test on WATECH EVB.</i></p>	<p>S-Parameter</p> <p><i>Test conditions, unless otherwise noted: 25 °C, VDD = 48 V, IDQ = 35 mA, Vgsp = Vgsp[1] - 1.8V, test on WATECH EVB.</i></p>
<p style="text-align: center;">ACPR_5M & ACPR_10M vs Pout - WCDMA</p>	<p style="text-align: center;">Gain&Eff vs Pout - WCDMA</p>
<p>WCDMA performance(ACPR)</p> <p><i>Test conditions, unless otherwise noted: 25 °C, VDD = 48V, IDQ = 35 mA, Vgsp = Vgsp[1] - 1.8V, 1C-WCDMA 5MHz Signal, 9.9 dB PAR @ 0.01% CCDF test on WATECH EVB.</i></p> <p><i>[1] IDQ_Peak=40mA</i></p>	<p>WCDMA performance(Gain+Eff)</p>

Pin Configuration and Description

 <p>Top view</p> <p>Exposed backside of the package is the ground terminal of the device.</p>		
Pin Configuration		
Pin Number	Label	Description
1	Gate1(carrier)	Gate-Source voltage of carrier
2	NC	Not Connected
3	Gate2(peak)	Gate-Source voltage of peak
4	Drain1(peak)	Drain-Source voltage of peak
5	NC	Not Connected
6	Drain2(carrier)	Drain-Source voltage of carrier

Package Marking and Dimensions

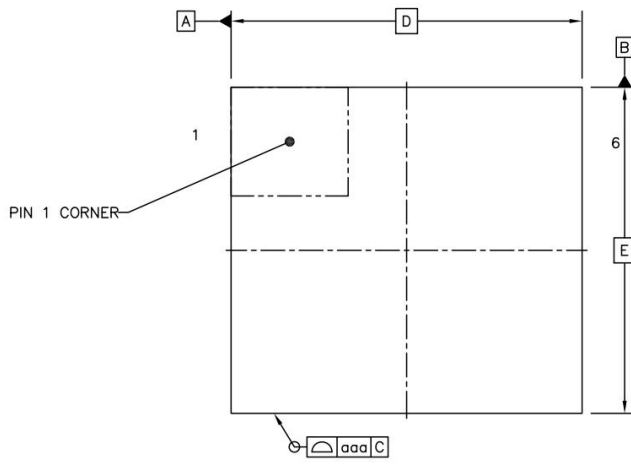


Line1 : fixed : device name in W/O

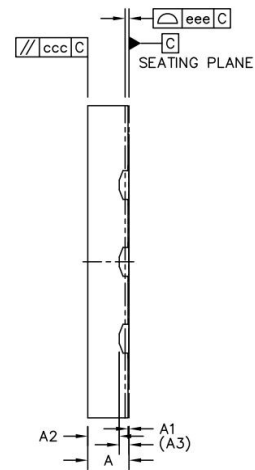
Line2 :unfixed : the last eight digits of Marking Lot No in W/O (Sample:EWRE0001)

Line3 :unfixed : "Date Code"+"_"+"JY"

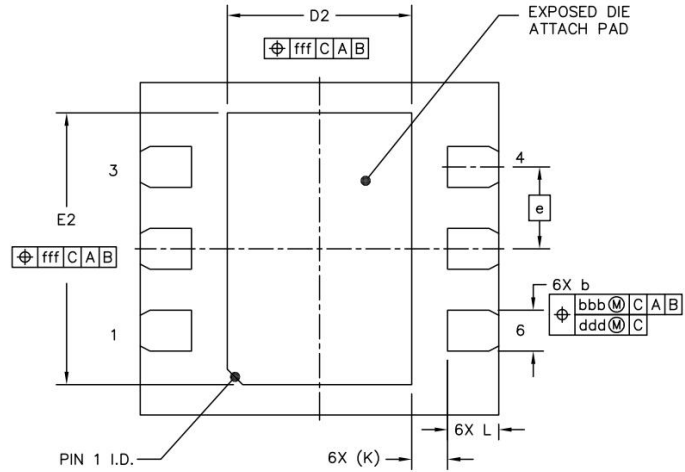
Marking



TOP VIEW



SIDE VIEW



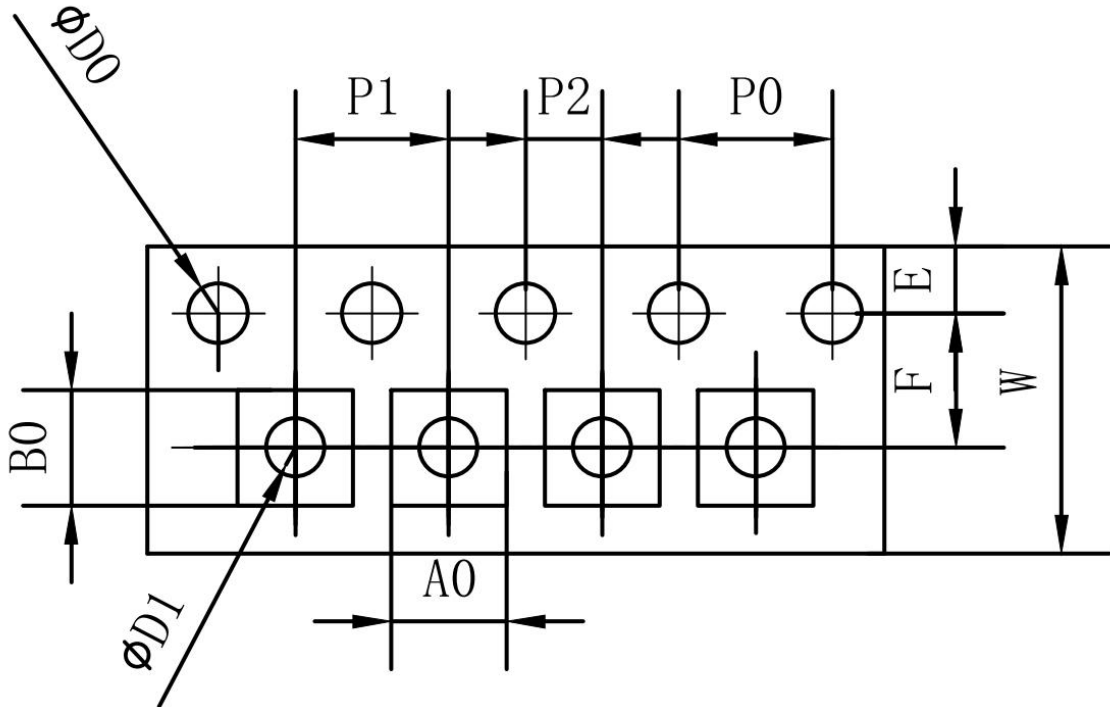
BOTTOM VIEW

	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	0.8	0.85	0.9
STAND OFF	A1	0	0.02	0.05
MOLD THICKNESS	A2	---	0.65	---
L/F THICKNESS	A3	0.203 REF		
LEAD WIDTH	b	0.75	0.8	0.85
BODY SIZE	X	7 BSC		
	Y	6.5 BSC		
LEAD PITCH	e	1.6 BSC		
EP SIZE	X	3.5	3.6	3.7
	Y	5.21	5.31	5.41
LEAD LENGTH	L	0.9	1	1.1
LEAD TIP TO EXPOSED PAD EDGE	K	0.7 REF		
PACKAGE EDGE TOLERANCE	aaa	0.1		
MOLD FLATNESS	ccc	0.1		
COPLANARITY	eee	0.08		
LEAD OFFSET	bbb	0.1		
	ddd	0.05		
EXPOSED PAD OFFSET	fff	0.1		

Package Dimensions


Packing Information

Package Type	Reel Size(inch)	Qty/Reel(pcs)	Qty/Box(pcs)	Qty/Carton(pcs)
DFN7*6.5-6L	13	3000	3000	15000



Item	W	E	F	D0	D1	P0	P2	P1	A0	B0
NOM	16.00	1.75	7.50	1.50	1.50	4.00	2.00	12.00	6.85	7.35
Tolerance	±0.30	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10

Handling Precautions

Parameter	Rating	Standard	
ESD – Human Body Model (HBM)	1A	ANSI/ESDA/JEDEC Standard JS-001	
ESD – Charged Device Model (CDM)	C1	ANSI/ESDA/JEDEC Standard JS-002	
MSL – 260°C Convection Reflow	MSL3	IPC/JEDEC Standard J-STD-020	

RoHS Compliance

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU.

Datasheet Status

Document status	Product status	Definition
Objective datasheet	Design simulation	Product objective specification
Preliminary datasheet	Customer sample	Engineering samples and first test results
Product datasheet	Mass production	Final product specification

Revision history

Document ID	Datasheet status	Release date	Version revision record
Rev1.0	Preliminary	Jul.2024	Preliminary
Rev2.0	Product	Dec.2024	Product



Abbreviations

Acronym	Definition
GaN	Gallium Nitride
CW	Continuous Waveform
VSWR	Voltage Standing Wave Ratio

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations and information about WATECH:

- Web: www.watechelectronics.com
- Email: MKT@huatai-elec.com

For technical questions and application information:

- Email: MKT@huatai-elec.com

Important Notice

Information in this document is believed to be accurate and reliable. However, WATECH does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

“Typical” parameters are the average values expected by WATECH in large quantities and are provided for information purposes only. All information and specifications contained herein are subject to change without notice and customers should obtain and verify the latest relevant information before placing orders for WATECH products.

The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information.

Applications that are described herein for any of these products are for illustrative purposes only. WATECH makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Customers are responsible for the design and operation of their applications and products using WATECH products, and WATECH accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the WATECH product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third-party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

WATECH products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of a WATECH product can reasonably be expected to result in personal injury, death or severe property or environmental damage. This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.